

Box III TEXT OF THE ABSTRACT (Continuation of item 5 of the first sheet)

In a wafer (1) a plurality of rows of head-to-be sections (2) to be thin film magnetic heads are aligned. The wafer includes: an inter-row cutting section (3) provided to be a position at which adjacent ones of the rows are to be separated; and an intra-row cutting section (4) provided to be a position at which adjacent ones of the head-to-be sections (2) in each of the rows are to be separated. In the wafer (1) a detection element (15) for detecting an amount of processing is formed near the medium-facing surface-side end of the intra-row cutting section (4). An electrode (16) for monitoring is formed in the inter-row cutting section (3) in the wafer (1) for electrically connecting the detection element (15) to an external device. Furthermore, a lead (17) for monitoring is formed in the intra-row cutting section for electrically connecting the electrode (16) to the detection element (15)

This Sheet Has Been Replaced

